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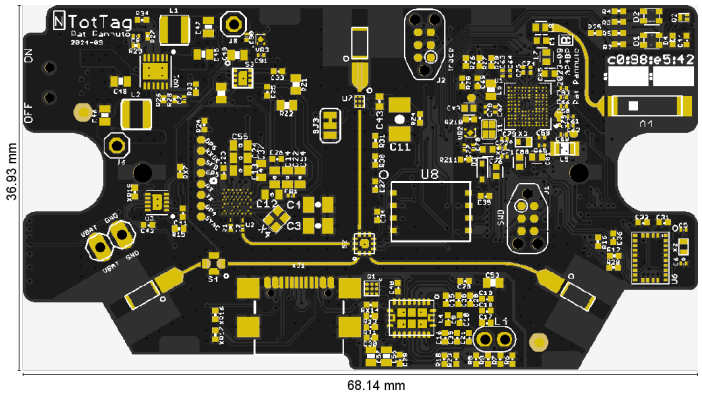
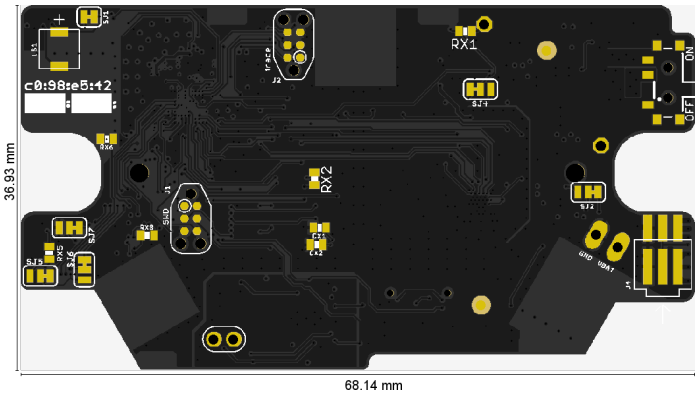
Single PCB View - Original

Top View	Bottom View
	

Summary - General - Original

PCB Size	68.136 mm x 36.932 mm		Customer Panel Size		
PCB Thickness	0.6 mm		Max. Aspect Ratio on PTH	5.9	
Copper Layers	4		Pressing Stages	1	
Surface Finish	unknown		Drill Hole Density	3155 Holes/dm^2	
Solder Mask	Both		Testable Points	815	
Solder Mask Color	Green		Min. SMD/BGA Size	0.17 mm	
Legend	Both		!HolesInPadPth!	Yes	
Legend Color	White		!HolesInPadBlind!	No	
Edge Connector Area	0 dm^2		Stacked Vias		
Peeloff Mask	No		Castellated	No	
Carbon Mask	No		Anomalies	No	

Summary - Copper Layer Minima - Original

Type	Copper Width	Critical Copper Width	Trace Width	Critical Trace Width	Copper to Copper Clr.	Trace to Trace Clr.	Same Net Clr.	Ring	Copper to Outline Clr.
	mm	mm	mm	mm	mm	mm	mm	mm	mm
Outer	1 0.105	2 0.127	3 0.127	4 0.127	5 0.101	6 0.102	7 0.020	8 0.051	9 0.292
Inner	10 0.027	11 0.120	12 0.127	13 0.127	14 0.102	15 0.102	16 0.038	17 0.050	18 0.305

Summary - Copper Layer Minima - Original

Type	Copper to Plated Clr.				Copper to NPTH Clr.			
	!Min.Clr.Overall!	!Min.Clr.toPad!	!Min.Clr.toTrace!	!Min.Clr.toRegion!	!Min.Clr.Overall!	!Min.Clr.toPad!	!Min.Clr.toTrace!	!Min.Clr.toRegion!
	mm	mm	mm	mm	mm	mm	mm	mm
Outer	19 0.177	20 0.177	21 0.178	22 0.178	23 0.212	24 0.212	25 0.305	26 0.305
Inner	27 0.178	28 0.178	29 0.178	30 0.178	31 0.305	32 0.305	33 0.327	34 0.305

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Summary - Sequences - Original

Type	Sequences	Tools	Min. End Dia.	Max. End Dia.	Holes	Routs	Ring on Outer	Ring on Inner	Hole to Copper Clr.
			mm	mm			mm	mm	mm
PTH	1	4	0.102	1.016	684	0	0.051	0.050	0.177
NPTH	1	4	0.650	1.800	12	0	>0.800	>0.800	0.212
Total	2	8	0.102	1.800	696	0	0.051	0.050	0.177

Summary - Rout - Original

Type	Tools	Min. End Dia.	Max. End Dia.	Rout Length
		mm	mm	mm
Plated				
NPTH				
Total				

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Stackup - Original

Pressing Stages	1

Files - Original

Initial	Renamed	Function	Position	Color	Thickness	
					Base	Finished
					mm	mm
stencil-top.pho	paste-top	paste	top			
silkscreen-top.pho	silk-top	silk	top	white	unknown	unknown
solder-mask-top.pho	mask-top	mask	top	black	unknown	unknown
copper-top.pho	top	outer	1		0.035	unknown
copper-inner-1.pho	in2	inner	2		0.035	unknown
copper-inner-2.pho	in3	inner	3		0.035	unknown
copper-bottom.pho	bot	outer	4		0.035	unknown
solder-mask-bottom.pho	mask-bot	mask	bottom	black	unknown	unknown
silkscreen-bottom.pho	silk-bot	silk	bottom	white	unknown	unknown
stencil-bottom.pho	paste-bot	paste	bottom			
drill-npth.pho	npth	unplated	1-4			
drill.pho	pth	plated	1-4			
outline.pho	outline	cad_outline	none			

PCB (Single) - Original

PCB Size	Outline Type	Outline Length	Outline Area	Copper Layers	PCB Thickness
mm x mm		mm	dm^2		mm
68.136 x 36.932	real	225.979	0.2206	4	0.600

Customer Panel (Delivery Array, Assembly Panel) - Original

Original Image	Panel Size	Left	Right	Top	Bottom	X Spacing	Y Spacing	PCB's	Depanel Rout Length
	mm x mm	mm	mm	mm	mm	mm	mm		mm

Thickness - Original

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Copper Layer Minima & Area - Original

File	Pos.	Copper Width	Critical Copper Width	Trace Width	Critical Trace Width	Copper to Copper Clr.	Same Net Clr.	Copper Area	
		mm	mm	mm	mm	mm	mm	dm^2	%
top	1	0.105	0.127	0.127	0.127	0.101	0.020	0.1418	64
in2	2	0.120	0.120	0.127	0.127	0.102	0.066	0.1708	77
in3	3	0.027	0.152	0.152	0.152	0.102	0.038	0.1110	50
bot	4	0.152	0.152	0.152	0.152	0.102	0.106	0.1479	67

Copper Layer Minima - Copper to Drill Minima - Original

File	Pos.	Ring					Copper to Drill Clr.		Copper to Outline Clr.			
		Overall	Via	Laser Via	Comp.	Mech.	Plated	NPTH	Overall	to Pad	to Trace	to Region
		mm	mm	mm	mm	mm	mm	mm	mm	mm	mm	mm
top	1	0.051	0.051		0.254		0.177	0.212	0.292	0.315	0.334	0.292
in2	2	0.050	0.050		0.250		0.178	0.305	0.305	0.426	>1.600	0.305
in3	3	0.050	0.050		0.250		0.178	0.305	0.305	0.489	0.540	0.305
bot	4	0.051	0.051		0.250		0.178	0.305	0.305	0.310	0.324	0.305

Copper Layers - Copper to Copper Clearances - Original

File	Pos.	Copper to Copper Clr.				
		Overall	Pad to Pad	Pad to Track	Track to Track	Trace to Trace
		mm	mm	mm	mm	mm
top	1	0.101	0.120	0.102	0.101	0.102
in2	2	0.102	0.127	0.102	0.102	0.116
in3	3	0.102	0.127	0.102	0.102	0.102
bot	4	0.102	0.127	0.102	0.102	0.102

Copper Areas - Original

Side	Total	Free of				Edge Connectors		
		Solder Mask (as supplied)	Solder Mask (open vias)	Gold Mask	Silver Mask	Fingers	Finger Size	Total Area
	dm^2	dm^2	dm^2	dm^2	dm^2		mm x mm	dm^2
Top (incl. 1/2 plated holes and routs)	0.1516	0.0244	0.0382					
Bottom (incl. 1/2 plated holes and routs)	0.1577	0.0074	0.0214					
Total (incl. plated holes and routs)	0.3093	0.0317	0.0596			0		
Plated holes and routs	0.0245	0.0011	0.0245					
Top (without plated holes and routs)	0.1393	0.0238	0.0259					
Bottom (without plated holes and routs)	0.1455	0.0068	0.0092					
Total (without plated holes and routs)	0.2848	0.0306	0.0351					

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Drill Tools - Original

File	Tool Nr.	Span	Type	Function	Method	Filled Via	Counter	Dia.	Tol. -	Tol. +	Holes in PCB	Routs in PCB	Double Hits	Predrill Hits
								mm	mm	mm				
npth	10	1-4	NPTH	mech.	mech.	unknown	unknown	1.800	0.000	0.000	2	0	0	0
npth	11	1-4	NPTH	mech.	mech.	unknown	unknown	1.016	0.000	0.000	6	0	0	0
npth	12	1-4	NPTH	mech.	mech.	unknown	unknown	0.900	0.000	0.000	2	0	0	0
npth	13	1-4	NPTH	mech.	mech.	unknown	unknown	0.650	0.000	0.000	2	0	0	0
pth	10	1-4	PTH	comp.	mech.	unknown	unknown	1.016	0.000	0.000	4	0	0	0
pth	11	1-4	PTH	comp.	mech.	unknown	unknown	1.000	0.000	0.000	2	0	0	0
pth	12	1-4	PTH	via	mech.	unknown	unknown	0.203	0.000	0.000	542	0	0	0
pth	13	1-4	PTH	via	mech.	unknown	unknown	0.102	0.000	0.000	136	0	0	0

Drill Tools - Drill vs Copper - Original

File	Tool Nr.	Span	Type	Function	Method	Dia.	Ring on Outer	Ring on Inner	Min. Pad Size	Via in Pad	Plated to Copper Clr.			
											!Min.Clr.Overall!	!Min.Clr.toPad!	!Min.Clr.toTrace!	!Min.Clr.toRegion!
						mm	mm	mm	mm		mm	mm	mm	mm
npth	10	1-4	NPTH	mech.	mech.	1.800	>0.800	>0.800						
npth	11	1-4	NPTH	mech.	mech.	1.016	>0.800	>0.800						
npth	12	1-4	NPTH	mech.	mech.	0.900	>0.800	>0.800						
npth	13	1-4	NPTH	mech.	mech.	0.650	>0.800	>0.800						
pth	10	1-4	PTH	comp.	mech.	1.016	0.254	0.254	1.524		0.356	>0.800	>0.800	0.356
pth	11	1-4	PTH	comp.	mech.	1.000	0.250	0.250	1.500		0.368	0.703	>0.800	0.368
pth	12	1-4	PTH	via	mech.	0.203	0.051	0.050	0.303	3	0.177	0.177	0.178	0.178
pth	13	1-4	PTH	via	mech.	0.102	0.051	0.051	0.204	46	0.178	0.179	0.178	0.178

Sequences - Original

Span	Type	Tools	Min. End Dia.	Max. End Dia.	Holes	Ring on Outer	Ring on Inner	Hole to Copper Clr.	Hole to Hole Clr., within Seq.		Overlapping Holes, within Seq.	Hole to Hole Clr., between Seqs		Hole to Outline Clr.	Slot to Outline Clr.
									Any Net	Diff. Net		Any Net	Diff. Net		
			mm	mm		mm	mm	mm	mm	mm		mm	mm	mm	mm
1-4	PTH	4	0.102	1.016	684	0.051	0.050	0.177	0.207	0.229	No	>0.800	>0.800	0.476	>6.400
1-4	NPTH	4	0.650	1.800	12	>0.800	>0.800	0.212	1.016		No	0.356		0.965	>6.400
All	All	8	0.102	1.800	696	0.051	0.050	0.177	0.207	0.229	No	0.356	>0.800	0.476	>6.400

Rout Tools - Original

File	Tool Nr.	Type	Tool Dia.	End Dia.	Rout Length	Nibble Count
			mm	mm	mm	

Routed Holes - Original

File	Hole Nr.	Instances	X Size	Y Size	Rout Length	Nibble Count
			mm	mm	mm	

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Sequences Analysis - Original

File	Pos.	Stacked Vias	Overlapped Vias	Via Plug Clr.	Top Tool			Bottom Tool		
					Top Drill File	Tool Nr.	Dia.	Bottom Drill File	Tool Nr.	Dia.
				mm			mm			mm

SMD (Incl. BGA) - Original

	SMD (Incl. BGA)				SMD (Excl. BGA)	BGA				
Side	Pads	Min. Pad	Pitch of Min. Pad	Solder Mask Defined Pads	Pads	Pads	Min. Pad	Min. Pitch	All Tracks Centered	Drilled Pads
		mm	mm				mm	mm		
Top	625	0.170	0.365	8	494	131	0.200	0.350	Yes	Yes
Bottom	58	0.635	1.016	0	58	0				
Both	683	0.170	0.365	8	552	131	0.200	0.350	Yes	Yes

Solder Mask - Original

Side	Mask to Mask Clr.	Web	Ring on Cu Defined Pads	Ring on SM Defined Pads	Mask to Copper Clr.	Mask Opening	Fully Covered Via Holes	Partly Covered Via Holes	One Side Covered Vias	Both Sides Covered Vias	No Side Covered Vias
	mm	mm	mm	mm	mm	mm					
Top	0.120	0.044	0.029	>0.250	0.000	0.178	Yes	Yes			
Bottom	0.105	0.105	0.032	>0.250	0.020	0.698	Yes	No			
Both	0.105	0.044	0.029	>0.250	0.000	0.178	Yes	Yes	Yes	Yes	No

Carbon Masks - Original

File	Position	Carbon Width	Carbon to Carbon Clr.	Clr. to Plated Hole	Clr. to Outline	Layer Area	
		mm	mm	mm	mm	dm^2	%

Peeloff Masks - Original

File	Position	Min. Peelable Width	Peelable to Peelable Clr.	Clr. to Plated Hole	Clr. to Outline	Layer Area	
		mm	mm	mm	mm	dm^2	%

Legend Layers - Original

File	Position	Legend Width	Legend to Legend Clr.	Legend to (Comp/SMD/BGA) Pad Clr.	Layer Area	
		mm	mm	mm	dm^2	%
silk-top	top	0.030	0.009	0.000	0.0155	7
silk-bot	bottom	0.102	0.050	0.000	0.0057	3

Gold Layers - Original

File	Position	Gold to Gold Clr.	Clr. to Outline	Layer Area	
		mm	mm	dm^2	%

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Heatsink Layers - Original

File	Position	Heatsink to Heatsink Clr.	Clr. to Outline	Layer Area	
		mm	mm	dm^2	%

Scoring - Minimum Clearance - Original

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Bare Board Test - Original

Side	Testable Points (TPs)	Max. TP Density	SMD Pads	Min. SMD Pad	Pitch of Min. SMD Pad	Edge Connector Fingers	Number of Nets
		TP/dm^2		mm	mm		
Top	751	7143	625	0.170	0.365	0	
Bottom	64	558	58	0.635	1.016	0	
Both	815	7143	683	0.170	0.365	0	219

DFM Classes - Original

			Standard						Advanced		
			1	2	3	4	5	6	7	8	9
Track & Gap	Min Clearance (Track-Track / Track-Pad / Pad-Pad)	0.101	0.300	0.250	0.200	0.150	0.130	0.120	0.100	0.075	0.060
	Min Track Width / Thermal Gap	0.120	0.300	0.250	0.200	0.150	0.130	0.120	0.100	0.075	0.060
Ring for IPC Class 2	Outer Min Layer Annular Ring	0.051	0.250	0.220	0.200	0.150	0.130	0.120	0.100	0.075	0.060
	Inner Min Layer Annular Ring	0.050	0.250	0.220	0.200	0.150	0.130	0.120	0.100	0.075	0.060
Aspect Ratio	Max Aspect Ratio for Plated Hole	5.900	8.000	8.000	8.000	8.000	10.000	10.000	10.000	10.000	10.000
Drill - Cu	Distance PTH to PTH	0.207	0.600	0.500	0.400	0.350	0.300	0.300	0.275	0.250	0.230
	Distance NPTH to Cu on inner layers	0.305	0.250	0.250	0.200	0.200	0.150	0.150	0.150	0.100	0.100
	Distance NPTH to Cu on outer layers	0.212	0.250	0.250	0.200	0.200	0.150	0.150	0.150	0.100	0.100
Cu Thickness	Max Cu Thickness that can be etched		0.175	0.140	0.105	0.070	0.070	0.035	0.035	0.035	0.017
Solder Mask	Solder Mask Annular Ring	0.000	0.100	0.075	0.050	0.050	0.050	0.050	0.040	0.030	0.010
	Solder Mask SolderWeb	0.044	0.150	0.125	0.100	0.100	0.100	0.100	0.080	0.075	0.075

Input Remarks - Original

Gerber Job File import: DISCREPANCY: Extra top layers mismatch between Gerber Job File and current job stackup.

Customer and Job Identification - Original

Customer			
Customer		Contact Person	
Email			

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Customer and Job Identification - Original

Job			
Article Id		Board Id	
DPMX Output Path	CH		

Comments - Original

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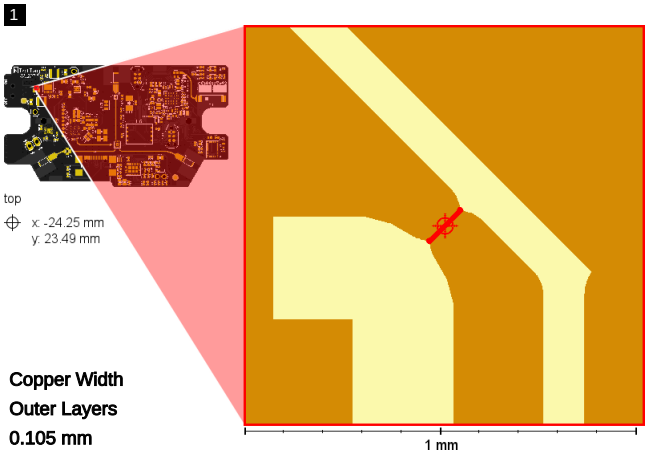
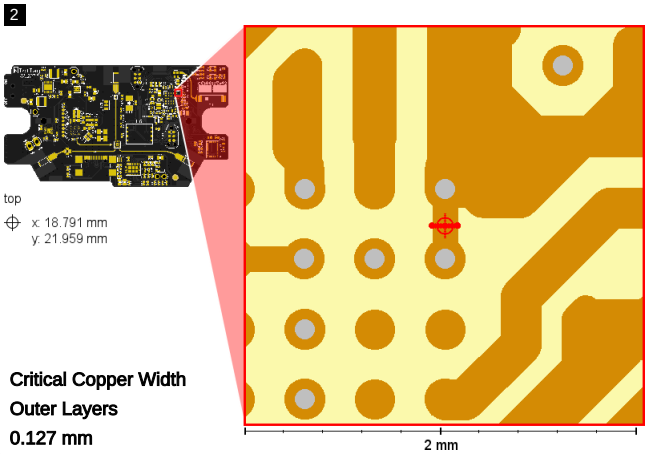
Summary Minimum Design Characteristics - Locations - Original

1



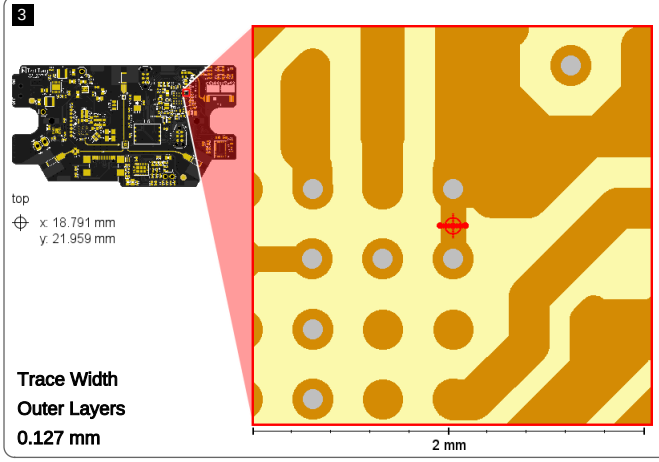
Copper Width
Outer Layers
0.105 mm

2



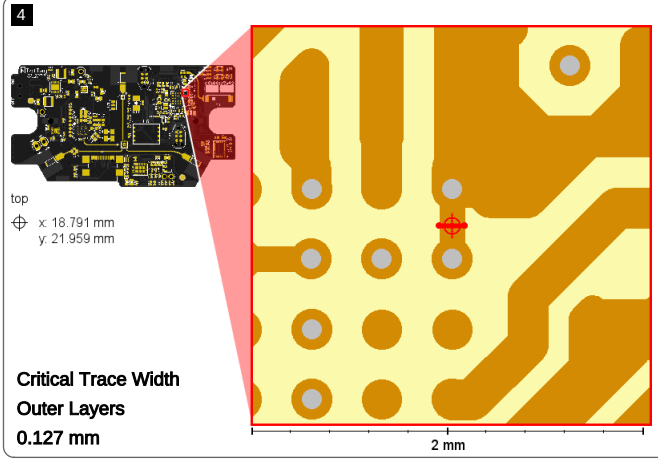
Critical Copper Width
Outer Layers
0.127 mm

3



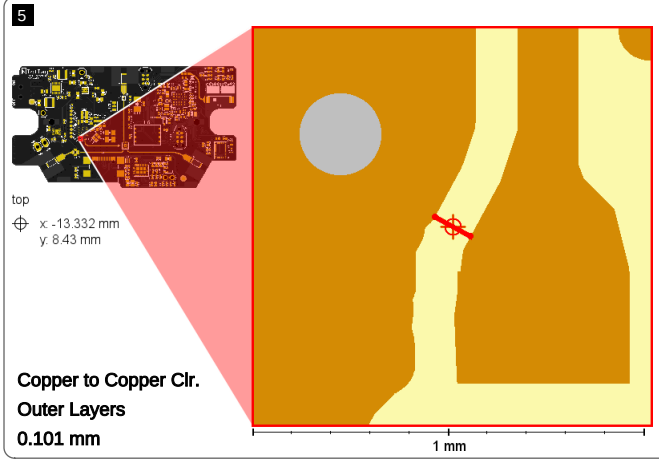
Trace Width
Outer Layers
0.127 mm

4



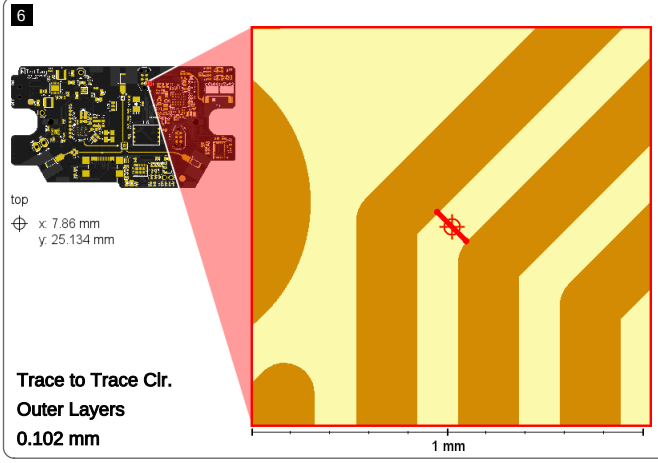
Critical Trace Width
Outer Layers
0.127 mm

5



Copper to Copper Clr.
Outer Layers
0.101 mm

6



Trace to Trace Clr.
Outer Layers
0.102 mm

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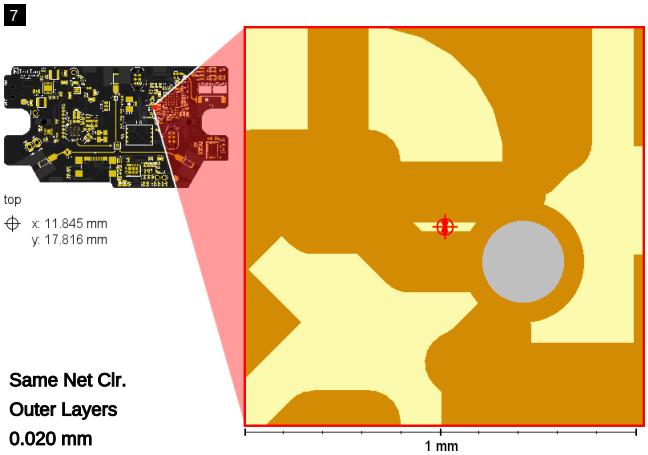
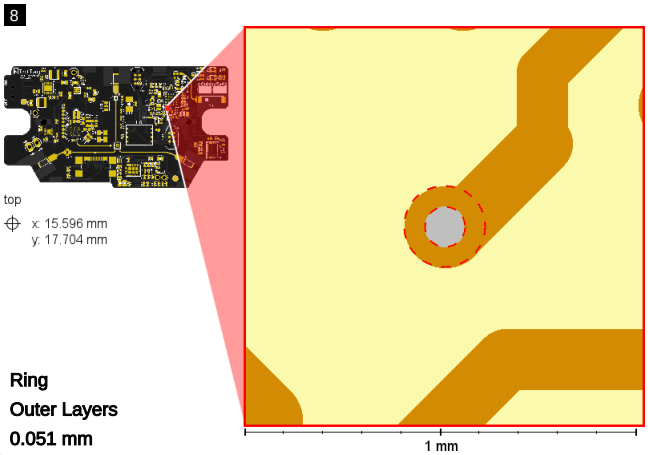


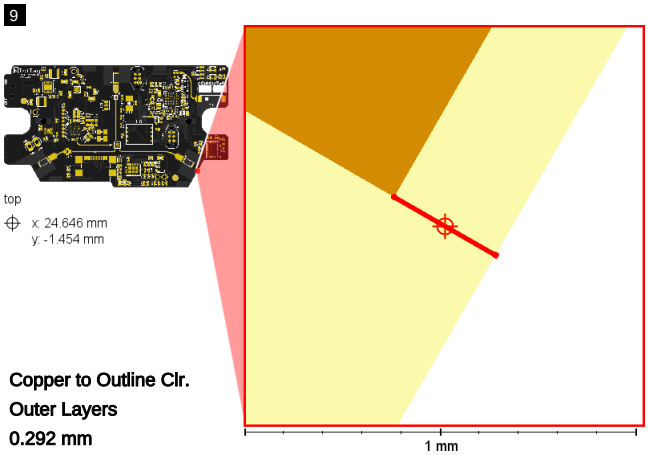
Same Net Clr.
Outer Layers
0.020 mm

8



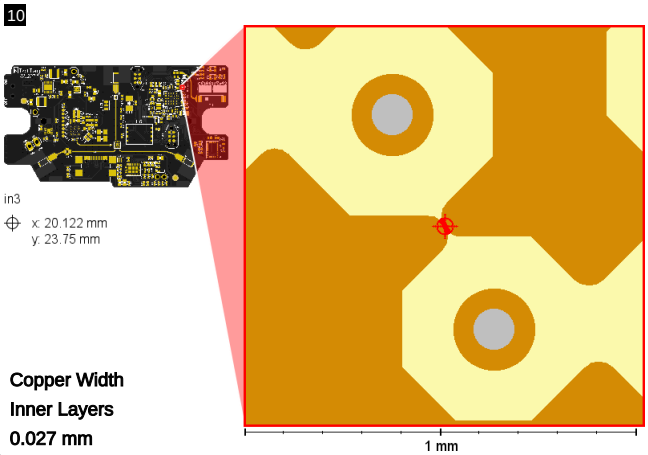
Ring
Outer Layers
0.051 mm

9



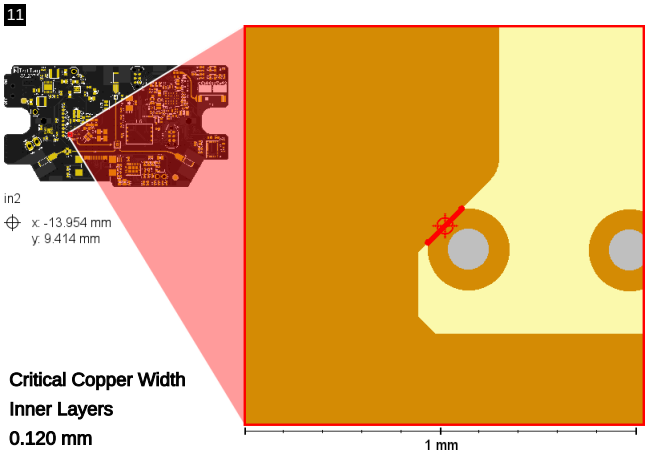
Copper to Outline Clr.
Outer Layers
0.292 mm

10



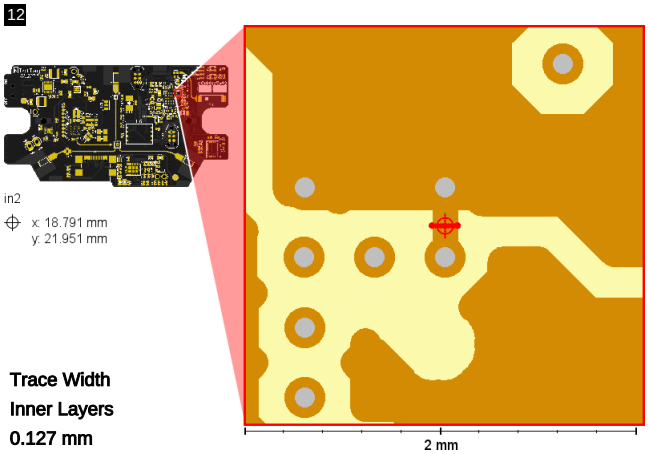
Copper Width
Inner Layers
0.027 mm

11



Critical Copper Width
Inner Layers
0.120 mm

12



Trace Width
Inner Layers
0.127 mm

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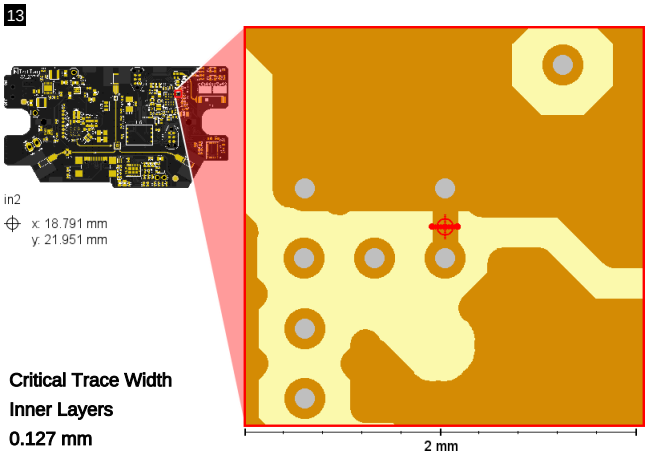
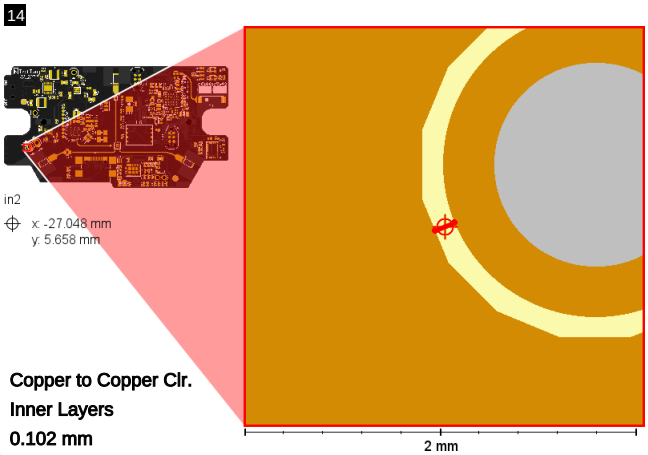


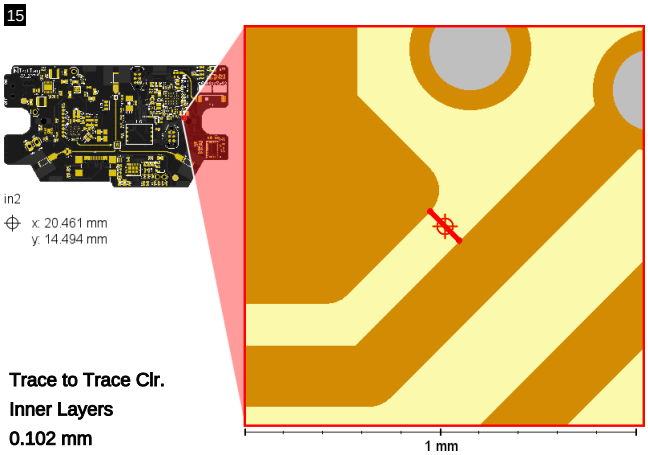
Critical Trace Width
Inner Layers
0.127 mm

14



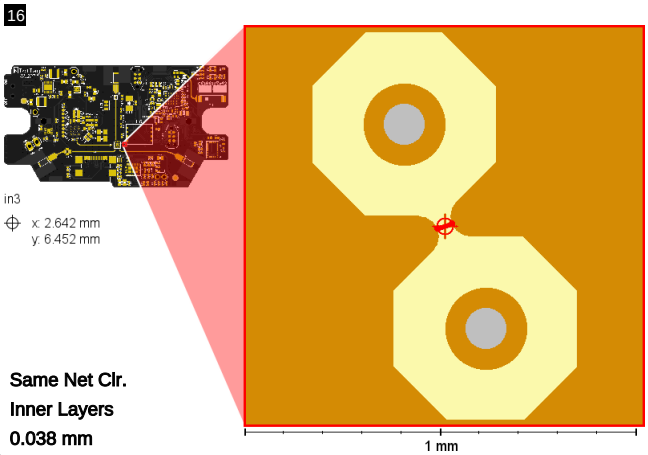
Copper to Copper Clr.
Inner Layers
0.102 mm

15



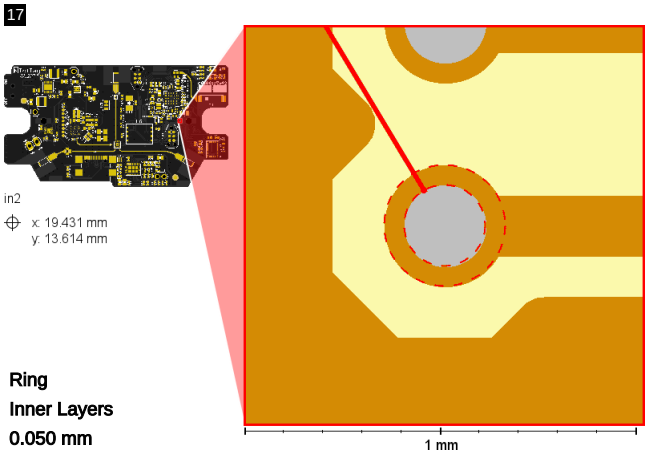
Trace to Trace Clr.
Inner Layers
0.102 mm

16



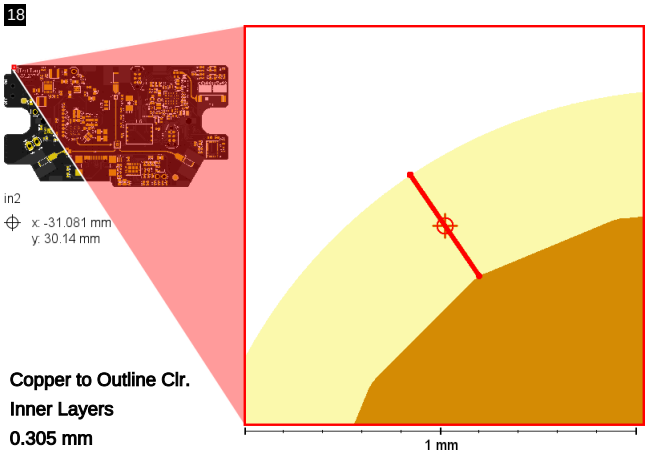
Same Net Clr.
Inner Layers
0.038 mm

17



Ring
Inner Layers
0.050 mm

18



Copper to Outline Clr.
Inner Layers
0.305 mm

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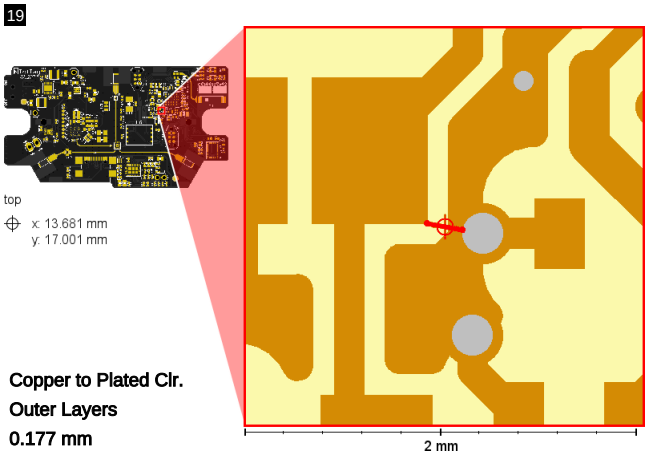
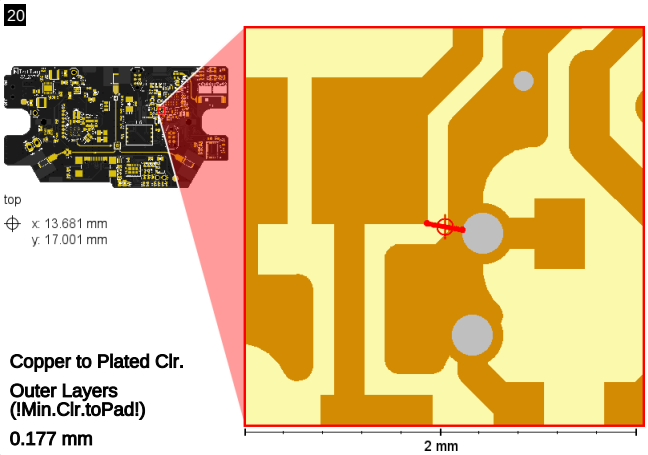
Report Generated on	Nov 13, 2024, 7:09:22 PM	Customer	
Board Id		Article Id	

19



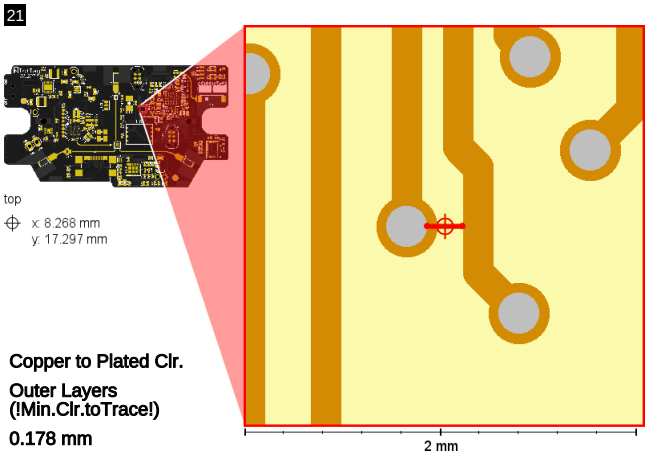
Copper to Plated Clr.
Outer Layers
0.177 mm

20



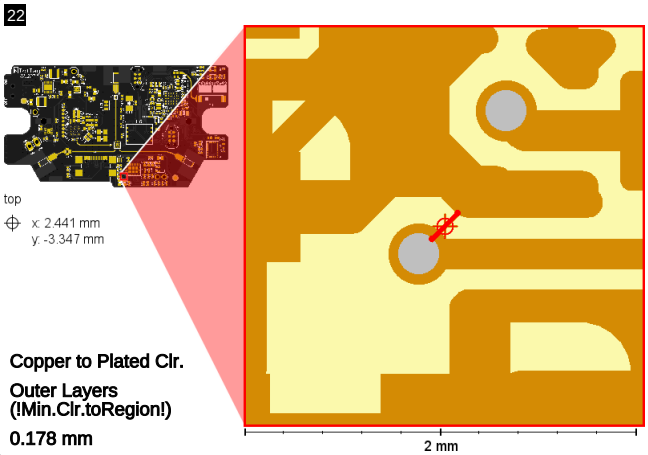
Copper to Plated Clr.
Outer Layers
(!Min.Clr.toPad!)
0.177 mm

21



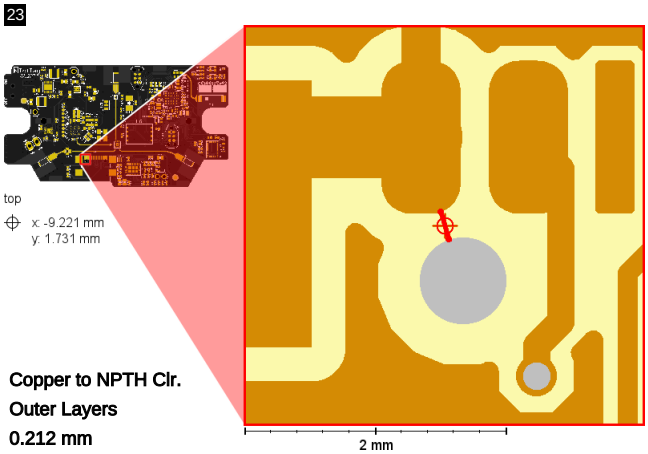
Copper to Plated Clr.
Outer Layers
(!Min.Clr.toTrace!)
0.178 mm

22



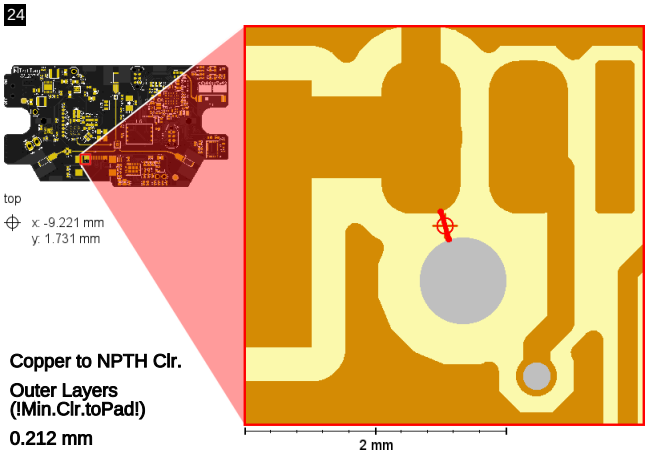
Copper to Plated Clr.
Outer Layers
(!Min.Clr.toRegion!)
0.178 mm

23



Copper to NPTH Clr.
Outer Layers
0.212 mm

24



Copper to NPTH Clr.
Outer Layers
(!Min.Clr.toPad!)
0.212 mm

Name	rev_61170.zip	Id.	22640 - QED With Image Data
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Board Id		Article Id	

Name	rev_61170.zip	Id.	22640 - QED With Image Data
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Board Id		Article Id